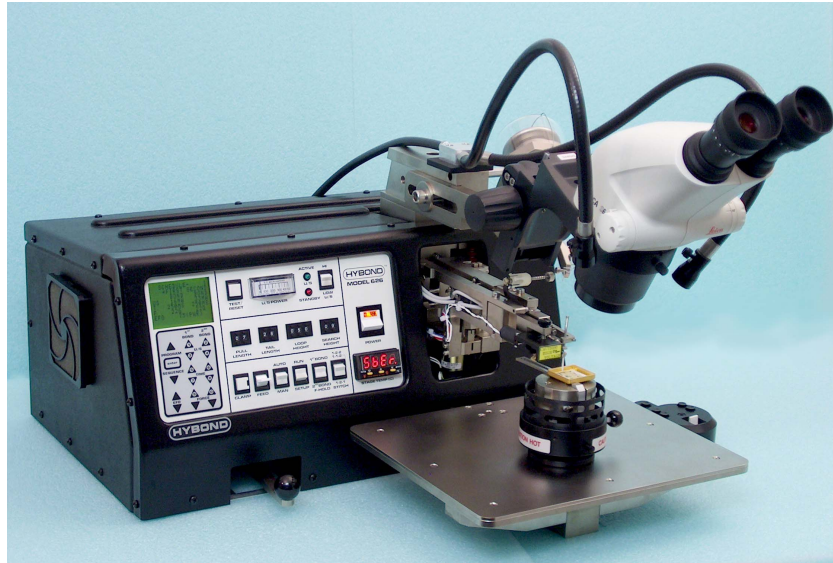




Soft Touch™

MODEL 626 MULTIPURPOSE DIGITAL THERMOSONIC WIRE BONDER

Ball Bonder, Wedge Bonder, Bump or Stud Bonder, Peg Bonder and more



STANDARD FEATURES:

- Motorized Z control in auto and manual modes (fast & slow speeds for manual).
- 75 bond schedules programmable in non-volatile memory.
- Selectable/adjustable Reset Heights (Constant or Adaptive).
- 1-2-2, 1-2-1 and 1-1-2 auto stitch or manual continuous stitch in manual & auto modes.
- Touch sensor bond actuation for variable bond height bonding.
- Audio and visual bond indicators.
- Static dissipative enclosure.
- 0.740in (18,8mm) max. vertical bonding window.
- Vertical deep access of 0.53in (13,5mm) when using a 0.750in. (19mm) capillary.
- Horizontal reach of 6.5 inches (165mm).
- Programmable loop and search heights.
- Built-in digital temperature controller.
- High/low power PLL ultrasonic generator.
- Swing away wire/ribbon clamps.
- 2 inch and 0.5 inch inertial spool holders.
- Z control by foot-switches or manipulator.
- **Ball, Wedge, Bump or Peg bond capable.**
- Electronic ball size control 0 - 4 x wire diameter.

Model 626 is a Deep Access, Long Reach Wire Bonder that **can operate as a Ball, Wedge, Bump or Peg bonder**. It can be used for wire diameters from 0.7 to 3.0mil (18 to 76 μ m) gold wire when in Ball/Bump bonder configuration, or wire diameters from 0.5 to 3.0 mil (12,7 to 76 μ m) and ribbon up to 1.0 x 20.0mil (25,4 x 510 μ m) for Wedge or Peg bonding configuration. The 626 was specifically designed for applications that require bonding at extreme height differences between 1st and 2nd bond and for bonding wires to sensitive devices such as gallium arsenide FET's, MMICs and LED's. Model 626's motorized wire feed and wire/ribbon clamping system provide superior wire/ribbon control and allow the operator to increase or decrease tail length in 1 mil (25 μ m) increments at a touch of a switch. The 626 shows actual units for set up of bond parameters. The change over from Ball bonder to Wedge bonder requires only a press of a button to turn EFO power to zero and a change from capillary to wedge tool. So versatile it can also be fitted with OP-54 for programmable motorized X-Y. For pick, place and bond feature add OP-47A.

Partial List of Available Options:

- **OP-06B:** Nikon SMZ745 Stereo Microscope.
- **CCTV-XX:** Microscope, Camera, Monitor, etc.
- **OP-08A-LED:** Dual Fiber Optic Illuminator.
- **OP-08R1-LED:** White LED Ring Illuminator.
- **OP-30A:** 8:1 X-Y Manipulator
- **OP-31:** Tool Heater and Temp. Controller.
- **OP-47A:** Beam Lead/Die Pick, Place & Bond.
- **OP-54:** Motorized X-Y and Y Step Back.
- **WST-15A:** Heated Work Stage, 2.125 in. top.
- **WST-19A:** Heated Work Stage, 4 x 6 in. top.
- **WST-65:** Heated Work Stage, 10 x 6 in top.
- **Wedge & Ball Tool** as ordered per application.

Specifications for Model 626:

- Ultrasonic (U/S) System: PLL self tuning 62.5KHz (nominal) system (± 2.5 KHz).
- U/S Power Range: 0-0.2 Watt on low setting and 0-2 Watts on high setting.
- Bond Time Range: 0mSec. to 900mSec.
- Bond Force Range: 12gr. to 250gr.
- Temperature Control Range: Ambient to 250 degrees Celsius.
- Bondable Wire Diameters: Ball configuration 0.7 to 3.0 mil (18 to 76 μ m), Wedge or Peg configuration 0.5 to 3.0 mil (12,7 to 76 μ m).
- Bondable Ribbon Dimensions: Up to 1 x 20 mil (25,4 x 510 μ m) in Wedge or Peg bonder mode.
- Bondable Wire/Ribbon Materials: Ball bonding mode: Gold and Platinum wire. Wedge bonding mode: Gold, Aluminum, Copper, Silver, Platinum.
- Bond Head Movement/Reach: Motorized (servo). Activated by manipulator mounted switches or foot switches. / Horizontal reach up to 6.5in (165mm).
- Bond Actuation/Bond Height Detect: By sensor at bond surface contact.
- Z Travel/Vertical Bonding Window: 0.750 in. (19,0mm)/0.740 in. (18,7mm).
- Table Motion: 4:1 manual manipulator, Standard.
- Input Power Requirements: 90 – 260VAC 50/60Hz @ 10A max.
- Minimum Bench Space Required: Width: 25in., Depth: 30in. (63,5 x 76,2cm).
- Unit Weight/Shipping Weight: 70 lbs. (31.8Kg)/150 lbs. (68,2Kg). Shipping weight may vary.
- Vacuum Requirement: Vacuum = 20 inHg min. (only for use with work stage if needed).
- Industry Standards: CE.

For more information contact us:



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